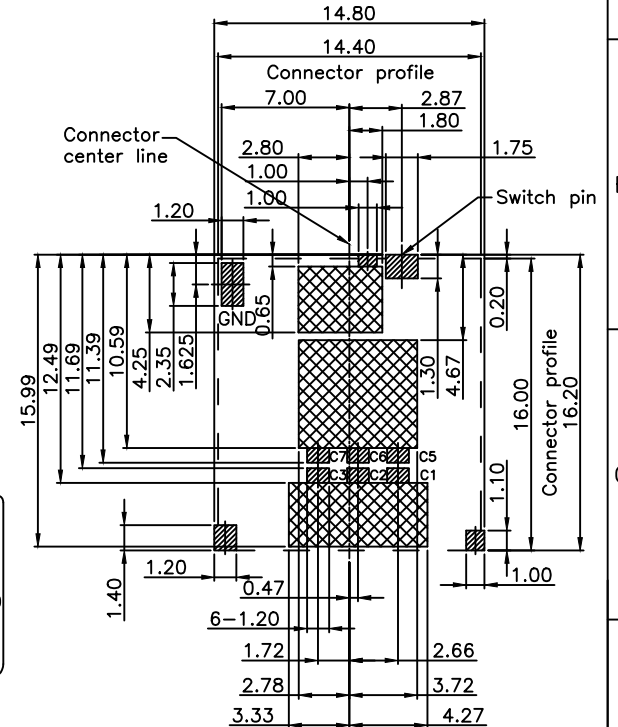
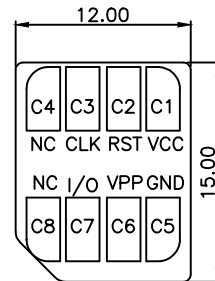
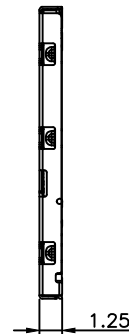
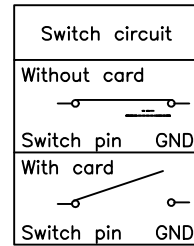
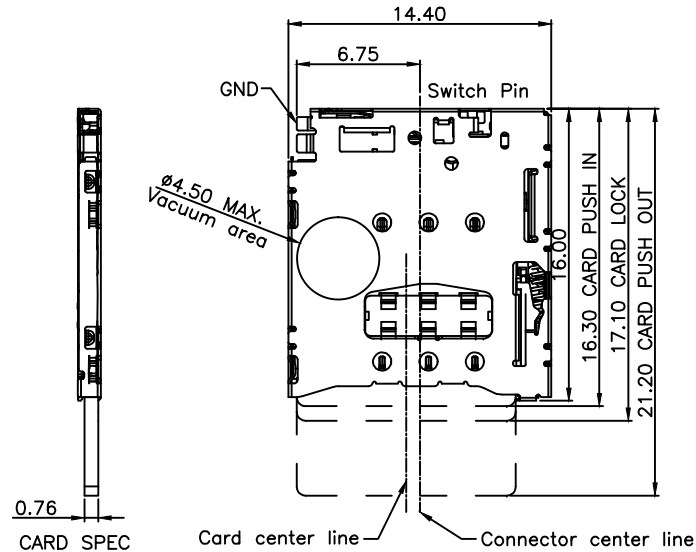


PROPRIETARY INFORMATION
COMPANY CONFIDENTIAL

REV.	ECN. NO.	DESCRIPTION	ENG	DATE
A		INITIAL	Dan	11/20/15'
B		ADD DIMENSION	Ethan	06/29/17'



P.C.B LAYOUT
TOP VIEW ±0.05

- NO PATTERN, VIA HOLE IN THIS AREA
- ONLY GND PATTERN AND GND VIA HOLE
- SOLDER AREA

MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0)
SHELL: STAINLESS STEEL
SOLDER PAD: STAINLESS STEEL, GOLD PLATING
TERMINAL: COPPER ALLOY, GOLD PLATED

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX
DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
CONTACT RESISTANCE: 100m OHMS MAX
INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
OPERATION TEMPERATURE: -20°C~+85°C

ITEM	NAME	Q'TY	DESCRIPTION
4	SOLDER PAD	1	C5210,Nickel 30u" Min under plating overall,Gold 0.5u" Min Plating On solder Area;
3	SHELL	1	SUS 304
2	TERMINAL	1	C5210, Nickel 30u" Min Under plating Overall, gold 0.8u" Min Plating on contact area.Gold 0.8u" Min Plating On solder Area;
1	HOUSING	1	LCP +30%GF UL94V-0 BLACK

GENERAL TOLERANCE	ANGLE TOLERANCE	DRAWN	DATE
X± 0.50	X°± 5.0°	Ethan	06/29/17'
.X± 0.38	.X°± 3.0°	CHECKED	DATE
.XX± 0.25	.XX°± 2.0°	APPROVED	DATE
.XXX± 0.15	.XXX°± 1.0°	LUCKY	06/29/17'

MATL	FINISH	SCALE	UNIT
SEE BOM	SEE NOTES	N/A	mm
SHEET 1 OF 1			

GENESIS TECHNOLOGY, INC	
TITLE:	MICRO SIM CARD, FEMALE, Top Mount, 6Pin H=1.25mm Push And Push, SMT, Gold Flash, Tape and Reel
PART NUMBER:	102-10005-01
DRAWING NO.	102-10005
SIZE	A4
REV.	B